IN THE CLAIMS:

Claims 8, 14-17 and 23-27 were previously cancelled. Claim 1 has been amended herein. All of the pending claims are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

1. (Currently amended) A method of fabricating a substrate assembly, comprising:

providing a substrate having a first surface and an opposing second surface;

forming a layer of resilient conductive material on at least one of the first and second surfaces of the substrate;

forming a plurality of electrically isolated spring-biased electrical contacts from the layer of resilient conductive material;

forming a plurality of elongate conductive traces from the layer of resilient conductive material, each elongate conductive trace associated with an electrically isolated spring-biased electrical contact of the plurality and extending therefrom, a portion of each elongate conductive trace being defined by a pair of substantially parallel cavities in the layer of resilient conductive material;

deforming at least a portion of at least one electrically isolated spring-biased electrical contact of the plurality of electrically isolated spring-biased contacts from a position co-planar with the associated elongated conductive trace and adjacent the at least one of the first and second surfaces to another position extending away from the at least one of the first and second surfaces of the substrate; and

treating the layer of resilient conductive material after forming the at least one electrically isolated spring-biased electrical contact to permanently enhance strength and elasticity of a portion of the resilient conductive material comprising the at least one electrically isolated spring-biased electrical contact.

2. (Previously presented) The method of claim 1, wherein forming a layer of resilient conductive material on at least one of the first and second surface of the substrate comprises:
providing a laminate sheet of the resilient conductive material; and
bonding the laminate sheet to the at least one of the first and second surfaces of the substrate.

3. (Previously presented) The method of claim 2, wherein bonding the laminate sheet to the at least one of the first and second surfaces of the substrate comprises adhering the laminate sheet to the at least one of the first and second surfaces of the substrate using an adhesive or bonding the laminate sheet to the at least one of the first and second surfaces of the substrate using a thermocompression bonding process.

4. (Previously presented) The method of claim 1, wherein forming a layer of resilient conductive material on at least one of the first and second surfaces of the substrate comprises forming the layer of resilient conductive material on the at least one of the first and second surfaces of the substrate using a deposition process.

5. (Previously presented) The method of claim 4, wherein the deposition process comprises chemical vapor deposition or sputtering.

6. (Previously presented) The method of claim 1, further comprising forming at least one via in the substrate, the at least one via underlying the at least one electrically isolated spring-biased electrical contact.

7. (Previously presented) The method of claim 6, wherein forming at least one via in the substrate further comprises forming a via opening only to the at least one of the first and second surfaces of the substrate.

8. (Cancelled)

9. (Previously presented) The method of claim 1, further comprising forming at least one contact element on a surface of the at least one electrically isolated spring-biased electrical contact.

10. (Previously presented) The method of claim 9, wherein forming at least one contact element further comprises forming a plurality of alternating grooves and ridges, forming at least one protrusion, or forming a roughened surface.

11. (Original) The method of claim 10, wherein forming a plurality of alternating grooves and ridges, forming at least one protrusion or forming a roughened surface is effected by etching.

12. (Previously presented) The method of claim 1, wherein forming the plurality of electrically isolated spring-biased electrical contacts in the layer of resilient conductive material comprises at least one of forming a cantilevered spring, forming a transversely deflecting hoop-shaped spring, forming a spiral-shaped spring, or forming a rosette spring.

13. (Previously presented) The method of claim 1, wherein forming the plurality of electrically isolated spring-biased electrical contacts and associated elongate conductive traces from the layer of resilient conductive material is effected by etching the layer of resilient conductive material.

14.-17. (Cancelled)

18. (Previously presented) The method of claim 1, further including disposing a dielectric layer overlying the layer of resilient conductive material, the dielectric layer being formed with at least one aperture therethrough substantially aligned with the at least one electrically isolated spring-biased electrical contact.

19. (Previously presented) The method of claim 18, further comprising forming the dielectric layer to be of sufficient thickness to encompass at least a portion of each lead element of an integrated circuit device contacting the at least one electrically isolated spring-biased electrical contact.

20. (Previously presented) The method of claim 18, further including forming the at least one aperture to be of frustoconical configuration.

21. (Previously presented) The method of claim 18, further including preforming the dielectric layer with the at least one aperture prior to disposing the dielectric layer over the layer of resilient conductive material.

22. (Previously presented) The method of claim 18, further including forming the dielectric layer in place over the layer of resilient conductive material and subsequently forming the at least one aperture therethrough.

23.-27. (Cancelled)